

Service Manual XGA COLOR MONITOR Model : L500B1

DAEWOO ELECTRONICS CO., LTD.

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SAFETY PRECAUTIONS

CAUTION: No modifications of any circuits should be attempted. Service work should be performed only after you are thoroughly familiar with all of the following safety checks and servicing guidelines.

♦ Safety Check

Care should be taken while servicing this analog color display because of the high voltages used in the deflection circuits. These voltages are exposed in such areas as the associated flyback and yoke circuits.

- ♦ Fire & Shock Hazard
 - Insert an isolation transformer between the analog color display and AC power line before servicing the chassis.
 - When servicing, pay close attention to the original lead dress especially in the high voltage circuit area; if a short circuit is found, replace all parts which have been overheated as a result of the short circuit.
 - All the protective devices must be reinstalled per original design.
 - Soldering must be inspected for possible cold solder points, frayed leads, damaged insulation, solder splashes or sharp solder points. Be certain to remove all foreign materials.

Implosion Protection

Picture tube in this monitor employs intergral implosion protection system, but care should be taken to avoid damage and scratching during installation. Only use same type replacement picture tubes.

IMPORTANT SAFETY NOTICE: There are special components used in this analog color display, which are important for safety. These parts are shaded on the schematic diagram and on the replacement parts list. It is essential that these critical parts should be replaced with manufacturer's specified parts to prevent X-Ray, shock, fire or other hazards. Do not modify the original design without getting written permission from DAEWOO ELECTRONICS CO. or this will void the original parts and labor warranty.

♦ X-Ray

WARNING: The only potential source of X-Ray is the picture tube. However when the high voltage circuitry is operating properly, there is no possibility of an X-Ray problem. The basic precaution which must be exercised is to keep the high voltage at the following factory recommended level.

NOTE: It is important to use an accurate, periodically, calibrated high voltage meter.

- To measure the high voltage, use a high-impedance high-voltage meter.
- Connect(-) to chassis and (+) to the CRT anode button.
- Turn the Contrast & Brightness Control fully counterclockwise.
- Measure the high voltage. The high voltage meter should indicate the following factory recommended levels.
- If the upper meter indication exceeds the maximum level, immediate service is required to prevent the possibility of premature component failure.
- To prevent X-Ray possibility, it is essential to use the specified picture tube.
- The normal high voltage is 25.5KV or below and must not exceed 29KV at zero beam current at rated voltage.

GENERAL SAFETY INFORMATION

• Terms in the manual

CAUTION Statements identify conditions or practices that could result in damage to the equipment or other property.

WARNING Statements identify conditions or practices that could result in personal injury or loss of life.

Terms as marked on equipment

CAUTION Statements indicate a personal injury hazard not immediately accessible as one reads the marking or a hazard which is properly included on the equipment itself.WARNING Statements are clearly concerning indicated personal injury hazards.

• Symbols in the manual

The symbols indicate where applicable cautionary or other information is to be found.

• Symbols as marked on equipment

Protective GROUND terminal



• High Voltage Warning And Critical Component Warning Label

The following warning label is on the CRT PWB shield case inside the unit.

Warning: This product includes critical mechanical and electrical parts which are essential for x ray protection. For continued safety, replace critical components that are indicated in the service manual with exact replacement parts given in the parts list. Operating high voltage with this product is 29Kv at minimum brightness. Refer to service manual for measurement procedures and proper service adjustments. **CAUTION:** Before servicing instruments covered by this service manual, its supplements, and addendum, please read and follow the SAFETY PRECAUTIONS of this manual.

NOTE: If unforeseen circumstances create conflict between the following servicing precautions and any of the safety precautions on page 1 of this manual, always follow the safety precautions. Remember: Safety First.

♦ General Servicing Precautions

- 1. Always unplug the AC power cord from the AC power source before: a. Removing or reinstalling any component, circuit board, module, or any other instrument assembly.
 - b. Disconnecting or reconnecting any electrical plug or other electrical connection.
 - c. Connecting a test substitute in parallel with an electrolytic capacitor in the instrument.

CAUTION: A wrong part substitution or incorrect polarity installation of electrolytic capacitors may result in a explosion.

- d. Discharging the picture tube anode.
- 2. Test high voltage only by measuring it with an appropriate high voltage meter or other voltage measuring device (DVM, FETVOM. etc.) equipped with a suitable high voltage probe. Do not test high voltage by "drawing an arc".
- 3. Discharge the picture tube anode only by: (a) first connecting one end of an insulated clip lead to the degaussing or line grounding system shield at the point where the picture tube socket ground lead is connected, and then (b) touching the other end of the insulated clip lead to the picture tube anode button, using an insulating handle to avoid personal contact with high voltage.
- 4. Do not any spray chemicals on or near this instrument, or any of its assemblies.
- 5. Unless otherwise specified in this service manual, only clean electrical contacts by applying the following mixture to the contacts with a pipe cleaner, cotton-tipped stick, or comparable nonabrasive applicator: 10% (by volume) Aceton and 90% (by volume) isopropyl alchohol (90%-99% strength).

CAUTION: This is a flammable mixture. Unless specified in this service manual, lubrication of contacts is not required.

- 6. Do not damage any plug/socket B+ voltage interlocks with which instruments covered by this service manual might be equipped.
- 7. Do not apply AC power to this instrument and/or any other of its electrical assemblies unless all the solid-state device heat sinks are correctly installed.
- 8. Always connect the test instrument ground lead to the appropriate instrument chassis ground before connecting the test instrument positive lead. Always remove the test instrument ground lead last.
- 9. Only use the test fixtures specified in this service manual with this instrument.

CAUTION: Do not connect the test fixture ground strap to any heatsink in this instrument.

♦ Electrostatically Sensitive (ES) Devices

Some semiconductor (solid state) devices can be damaged easily by static electricity. Such components are commonly called Electrostatically Sensitive (ES) Devices. The typical examples of ES devices are integrated circuits, some field-effect transistors, and semiconductor "chip" components. The following techniques should be used to help reduce the incidence of component damage caused by static electricity.

- 1. Immediately before handling any semiconductor component or semiconductor-equipped assembly, wipe off any electrostatic charge on your body by touching any known earth ground. Alternatively, obtain and wear a commercially available discharging wrist strap device which should be removed for potential shock reasons prior to applying power to the unit under testing conditions.
- 2. After removing the electrical assembly equipped with ES devices, place the assembly on a conductive surface such as aluminum foil to prevent electrostatic charge buildup or exposure to the assembly.
- 3. Only use a grounded-tip soldering iron to solder or unsolder ES devices.
- 4. Only use an anti-static type solder removal device. Some solder removal devices not classified as "antistatic" can generate enough electrical charges to damage ES devices.

5. Do not use freon-propelled chemicals. These can generate enough electrical charges to damage ES devices.

- 6. Do not remove a replacement ES device from its protective package until immediately before you are ready to install it. (Most replacement ES devices are packaged with leads electrically shorted together by conductive foam, aluminum foil, or comparable conductive material).
- 7. Immediately before removing the protective material from the leads of replacement ES devices, touch the protective material to the chassis or circuit assembly into which the device will be installed.

CAUTION: Be sure that no power is applied to the chassis or circuit, and observe all other safety precautions.

8. Minimize bodily movements when handling unpackaged replacement ES devices. (Otherwise harmful motion such as the brushing together clothes fabric or the lifting your foot from a carpeted floor can generate enough static electricity to damage ES devices).

General Soldering Guidelines

- 1. Use a grounded-tip, low-wattage soldering iron with appropriate tip size and shape that will maintain tip temperature between a 550°F-660°F (288°C-316°C) range.
- 2. Use an appropriate gauge of RMA resin-core solder composed of 60 parts tin/40 parts lead.
- 3. Keep the soldering iron tip clean.
- 4. Throughly clean the surface to be soldered. Use a small wire-bristle (0.5 inch or 1.25cm) brush with a metal handle. Do not use freon-propelled spray-on cleaners.

5. Use the following soldering technique:

- a. Allow the soldering iron tip to reach normal temperature (550°F to 660°F or 288°C to 316°C)
- b. Hold the soldering iron tip and solder strand against the component lead until the solder melts.
- c. Quickly move the soldering iron tip to the junction of the component lead and the printed circuit foil, and hold it there until the solder flows onto and around both the component lead and the foil.
- d. Closely inspect the solder area and remove any excess or splashed solder with a small wire-bristle brush.

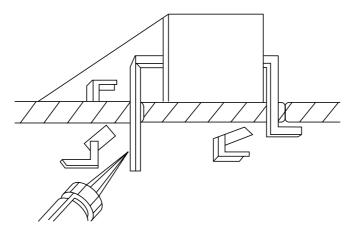


FIGURE 1. USE SOLDERING IRON TO PRY LEADS

• IC Removal/Replacement

Some utilized chassis circuit boards have slotted (oblong) holes through which the IC leads are inserted and then bent flat against the circuit foil. When holes are slotted, the following technique should be used to remove and replace the IC. When working with boards using the familiar round hole, use the standard technique as outlined in paragraphs 5 on the page under the title of general soldering guidelines.

Removal

- 1. Desolder and straighten each IC lead in one operation by gently prying up on the lead with the soldering iron tip as the solder melts.
- 2. Draw away the melted solder with an anti-static suction-type solder removal device (or with desoldering braid before removing the IC.

Replacement

- 1. Carefully insert the replacement IC in the circuit board.
- 2. Carefully bend each IC lead against the circuit foil pad and solder it.
- 3. Clean the soldered areas with a small wire-bristle brush. (It is not necessary to reapply acrylic coating to the area).

• "Small-Signal" Discrete Transistor Removal/Replacement

- 1. Remove the defective transistor by clipping its leads as close as possible to the component body.
- 2. Bend the ends of each of three leads remaining on the circuit board into a "U" shape.
- 3. Bend the replacement transistor leads into a "U" shape.
- 4. Connect the replacement transistor leads to the corresponding leads extending from the circuit board and crimp the "U" with long nose pliers to ensure metal-to-metal contact, then solder each connection.

Power IC, Transistor or Devices Removal/Replacement

- 1. Heat and remove all solders from the device leads.
- 2. Remove the heatsink mounting screw (if applicable).
- 3. Carefully remove the device from the circuit board.
- 4. Insert new device in circuit board.
- 5. Solder each device lead and then clip off excess lead.
- 6. Replace heatsink.

◆ Diode Removal/Replacement

- 1. Remove defective diode by clipping its leads as close as possible to diode body.
- 2. Bend the two remaining leads perpendicularly to the circuit board.
- 3. Observing diode polarity, wrap each lead out of the new diode around the corresponding lead on the circuit board.
- 4. Securely crimp each connection and solder it.
- 5. Inspect the solder joints of the two "original" leads on the circuit board copper side. If they are not shiny, reheat them and apply additional solder if necessary.

Panel Size		15.1-inch (38cm) diagonol				
Pixel Pitch		0.3 x 0.3 mm				
Synchronization Horizontal		30 - 62 KHz				
	Vertical	50 - 85 Hz				
Plug and Play		DDC1/2B/CI				
Power Saving		EPA, VESA DPMS, Nutek Compliant				
Power Source Power Consumption Dimension-W x H x D(net/gross)		100-240 Vac, 50/60Hz (Free Voltage)				
		DC12V, 3A				
		21W(without adapter)/26W(with adapter) 390 x 401.5 x 73.5mm/502 x 502 x 242mm				
					Weight(net/gross)	
		9.9/14.11bs				
Tilt/Swivel Range Tilt		5° forward, 30° backward				
	Swivel	\pm 90° leftward, rightward				
Operating Temperature		10 ~ 40°C /50 ~ 104°F				

TECHNICAL INFORMATION

GENERAL INFORMATION

This TFT LCD monitor automatically scans all horizontal frequencies from 30KHz to 62KHz, and all vertical frequencies from 50Hz to 85Hz. This TFT LCD monitor supports IBM PC, PC/XT, PC/AT, personal System/2 (PS/2), Apple Macintosh, and compatible users crisp text and vivid color graphics display when using the following graphics adapters : (VGA, Super VGA, VESA and XGA and Apple Macintosh Video Card). And so, this TFT LCD monitor has a maximum horizontal resolution of 1024 dots and a maximum vertical resolution of 768 lines for superior clarity of display.

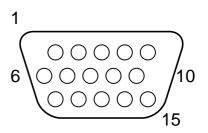
By accepting analog signal inputs which level is zero to 0.7 Volts. This TFT LCD monitor can display and 262, 144 colors depending on the graphics adapter and software being used. (available used to 8 bit panel is 16.7M colors)

ADJ	Adjustment
AFC	Automatic Frequency Control
CRT	Cathode Ray Tube
Def	Deflection
D.Y	Deflection Yoke
HVG	High Voltage Generator
H.SYNC	Horizontal Synchronization
OSC	Oscillator
P.S.U	Power Supply Unit
PWA	Printed Circuit Board Wiring Assembly
R.G.B	Red, Green, Blue
V.Sync	Vertical Synchronization

♦ Abbreviations

PIN CONNECTOR

Pin	Signal
1	Red
2	Green
3	Blue
4	GND
5	GND
6	GND - Red
7	GND - Green
8	GND - Blue
9	+5Vdc
10	GND - H.Sync
11	GND - V.Sync
12	Bi-directional Data (SDA)
13	Horizontal Sync
14	Vertical Sync (VCLK)
15	Data Clock (SCL)



Arrangement of 15-pin D-sub connector

CAUTIONS FOR ADJUSTMENT AND REPAIR

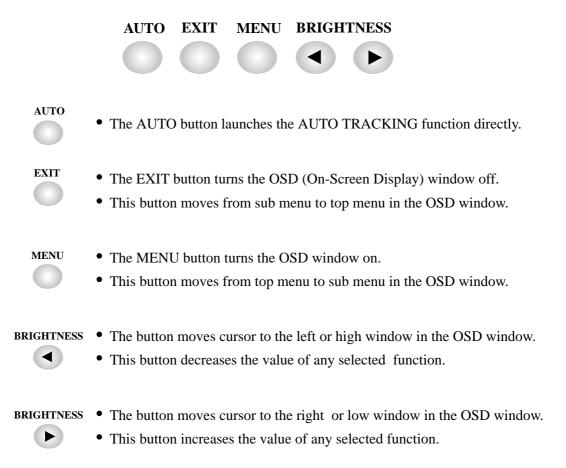
- Degaussing is always required when adjusting purity or convergence.
- The white balance adjustment has been done by a color analyzer in factroy. The adjustment procedure, described in the service manual is made by a visual check.
- Allow 20 minutes warm-up time for the display before checking or adjusting only electrical specification or function.
- Reform the leadwire after any repair work.

Caution For Servicing

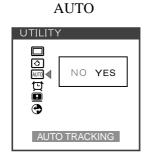
• In case of servicing or replacing CRT, high voltage sometimes remains in the anode of the CRT. Completely discharge high voltage before servicing or replacing CRT to prevent a shock to the serviceman.

OPERATION & ADJUSTMENT

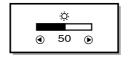
Control Panel



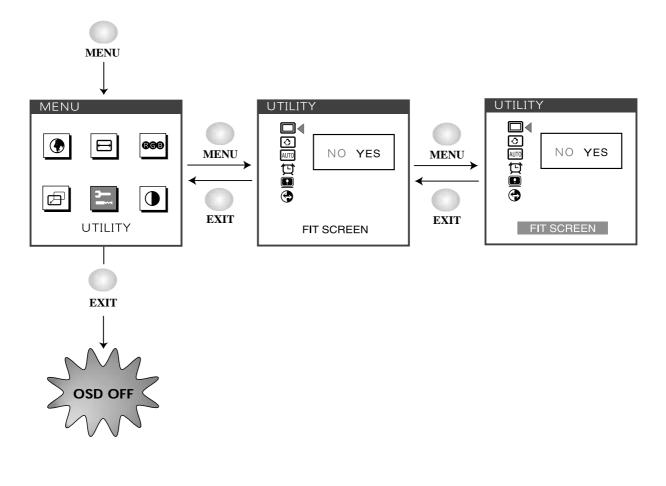
Hot Key



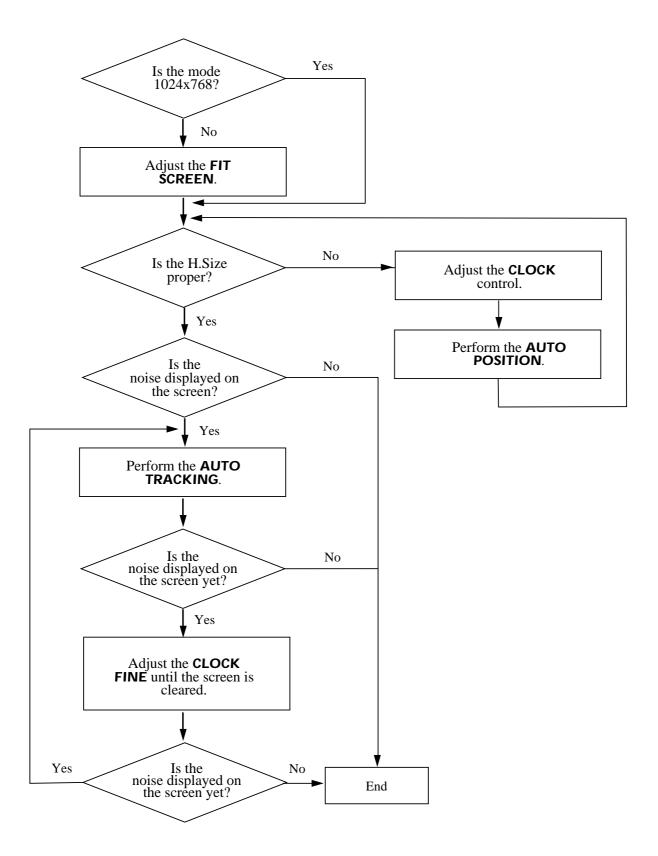
BRIGHTNESS



Key Process



Adjustment Procedure



OSD Functions

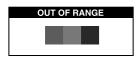
ICON	CONTROL	FUNCTIONS			
	LANGUAGE	Select language for OSD (5 languages).			
\longleftrightarrow	CLOCK	Adjust the width (horizontal size) of the screen image.			
<u>}</u> }}	CLOCK FINE	Sharpen the focus by aligning the illuminated pixels and adjust until the screen image looks focused, crisp and sharp. Adjusting the CLOCK FINE after the CLOCK adjustment will produce a clear screen.			
₿к	COLOR TEMP	Choose different preset color temperatures or set your own customized color parameters.			
R	RED CONTROL	Adjust the red color.			
G	GREEN CONTROL	Adjust the green color.			
B	BLUE CONTROL	Adjust the blue color.			
þ	H. CENTER & V. CENTER	Adjust the position of the display horizontally(left or right) and vertically (up or down).			
	FIT SCREEN	Make characters of displayed text easier to read (only for resolutions lower than 1024x768).			
ি	SMART SCALING	Adjust the display image quality (if the screen proceed to scaling up).			
AUTO	AUTO TRACKING	Adjust the horizontal & vertical picture image quality and size.			
É	OSD TIME OUT	Adjust the display OSD Menu.			
	STATUS	Display horizontal & vertical frequency and polarity.			
¢	RECALL	Reset the screen to the Factory Preset Display Settings.			
	AUTO POSITION	Choose automatically the proper horizontal position and vertical position & size of the screen image.			
	CONTRAST	Adjust the contrast of image, the difference between light and dark areas on the screen.			

Self Diagnosis

When the monitor doesn't display, if you press any key, Self Diagnosis screen is displayed. Self Diagnosis function checks if the status of the monitor is No Signal or Out of range.



No Signal screen is displayed when the D-Sub signal connector is not connected or the status of the monitor is on DPMS mode.



Out of Range screen is displayed when the applied frequency is under or over normal range.

 Normal range (Non-interlaced mode only)
 H: 30 - 62 KHz (1024 dot Max)
 V: 50 - 85 Hz (768 dot Max)

ALIGNMENT PROCEDURE

Standard Check point

- 1. Power source : 100 240Vac, 50/60Hz.
- 2. Aging : Take at least 20 minutes warm-up time.
- 3. Signal

Video input : Analog 0.7Vpp 75Ω terminal positive polarity Synchronizing : acceptable negative or positive at TTL level Resolution Horizontal : 1024 max.

Vertical : 768 max.

Frequency

Horizontal : 30KHz - 62KHz

Vertical: 50Hz - 85Hz (available only non interlace mode)

Adjustment

- 1. Smart scaling set to 69%.
- 2. Contrast set to 100%
- 3. Brightness set to 50%
- 4. Switching to factory alignment mode

Press power key with Auto key at the power off status.

5. Video level adjustment

Receive stair pattern of 16 step (doesn't care any mode).

Readjust coarse R, G, B in TDA8752 menu before saturaton point.

6. Set up the tracking

See the user's manual at page 8th.

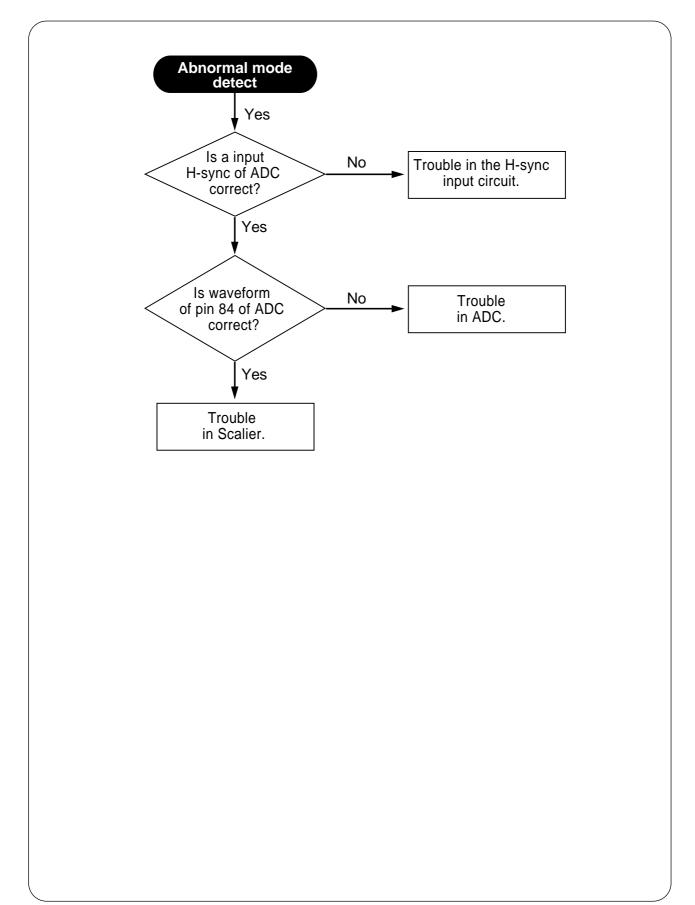
7. Switching to user's mode

If turn-off and turn-on then switched to user's mode.

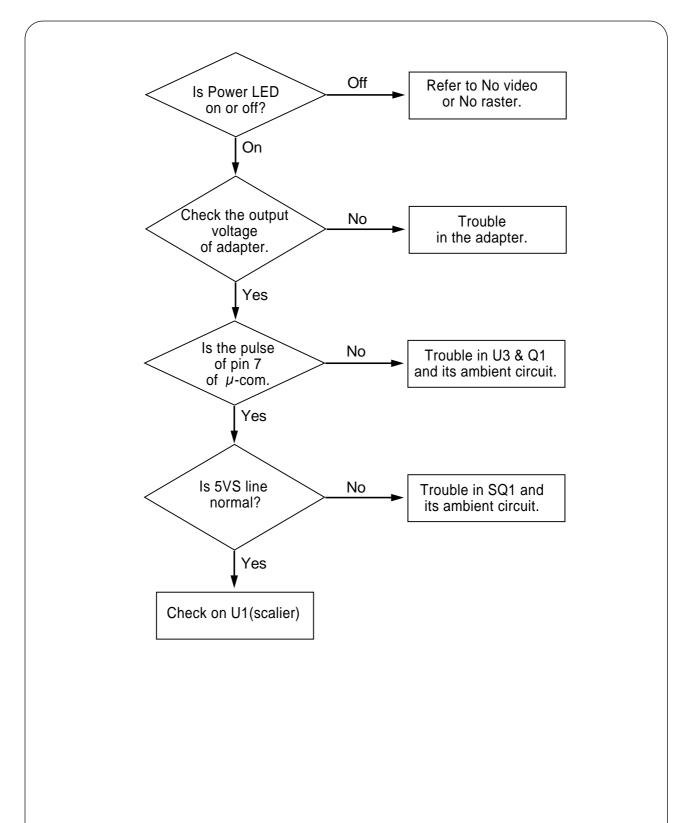
* All of adjusted data stores by fade out of OSD.

TROUBLESHOOTING HINTS

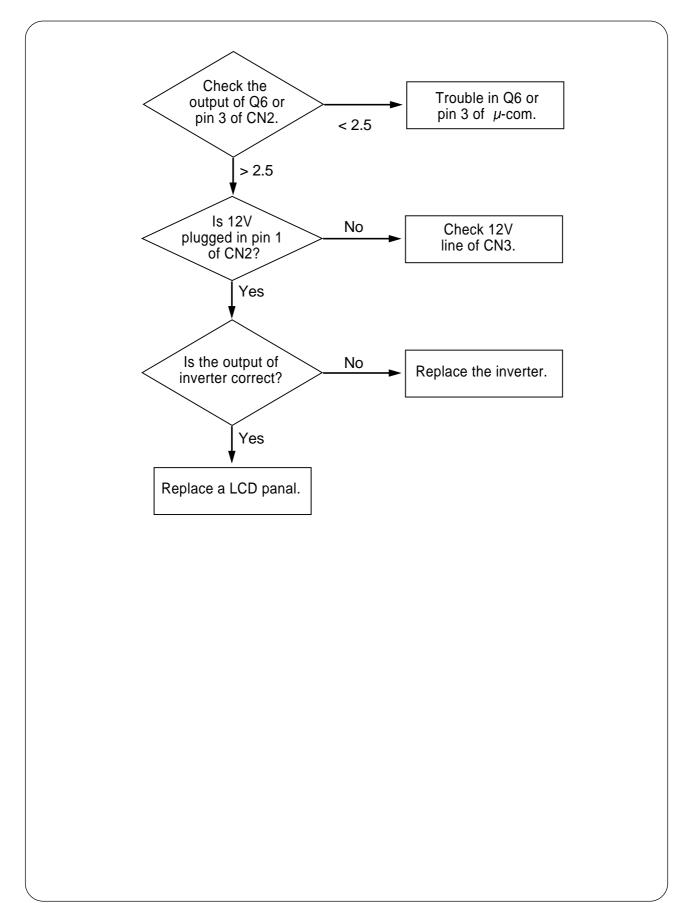
1. Abnormal mode detect



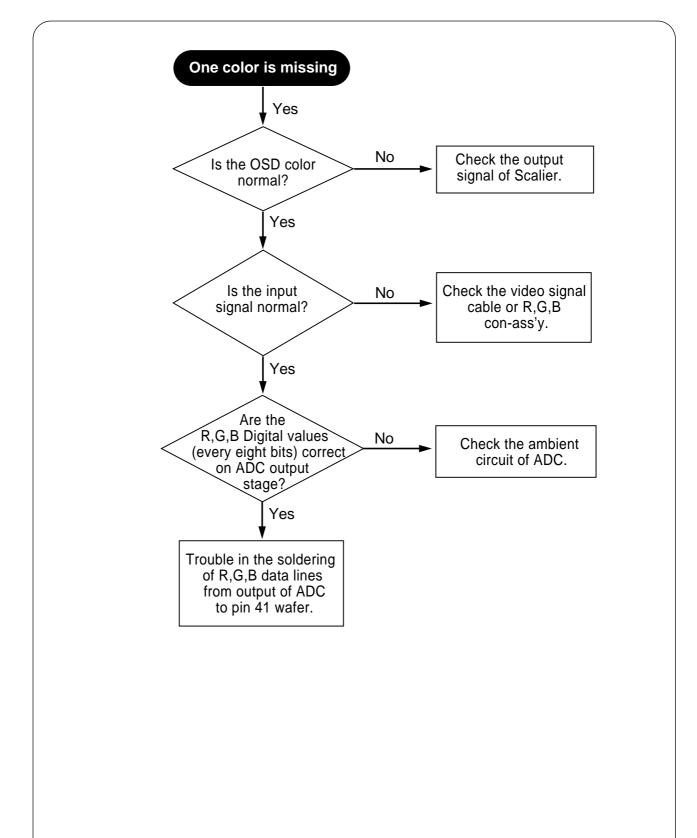
2. Trouble in Power on



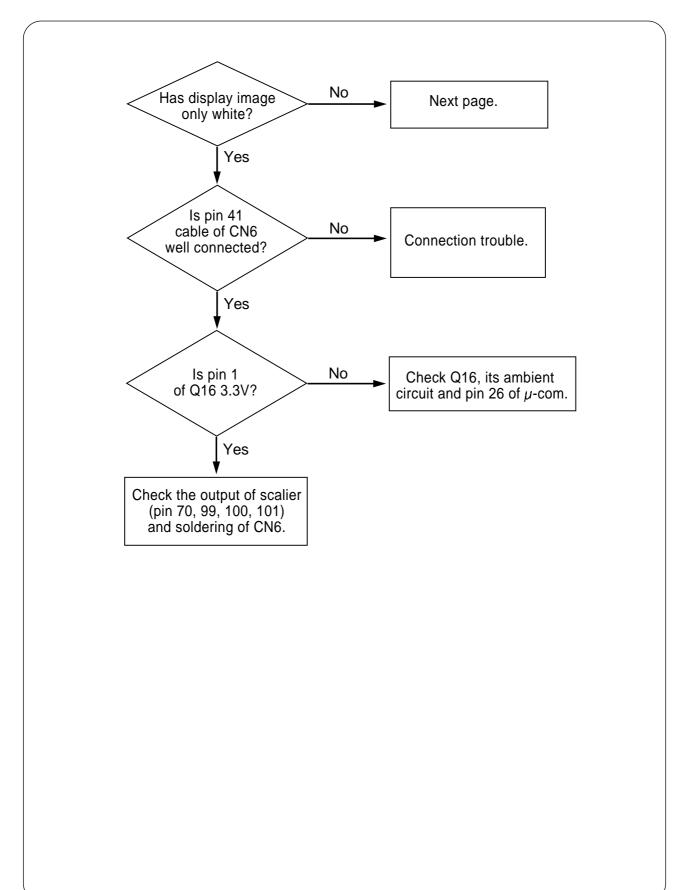
3. No Raster



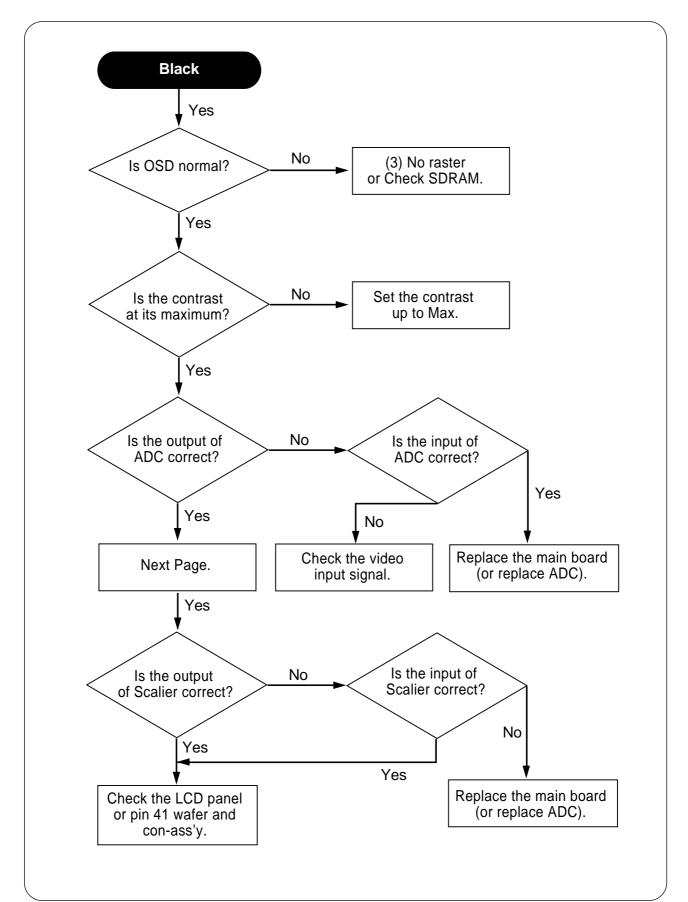
4. One color is missing



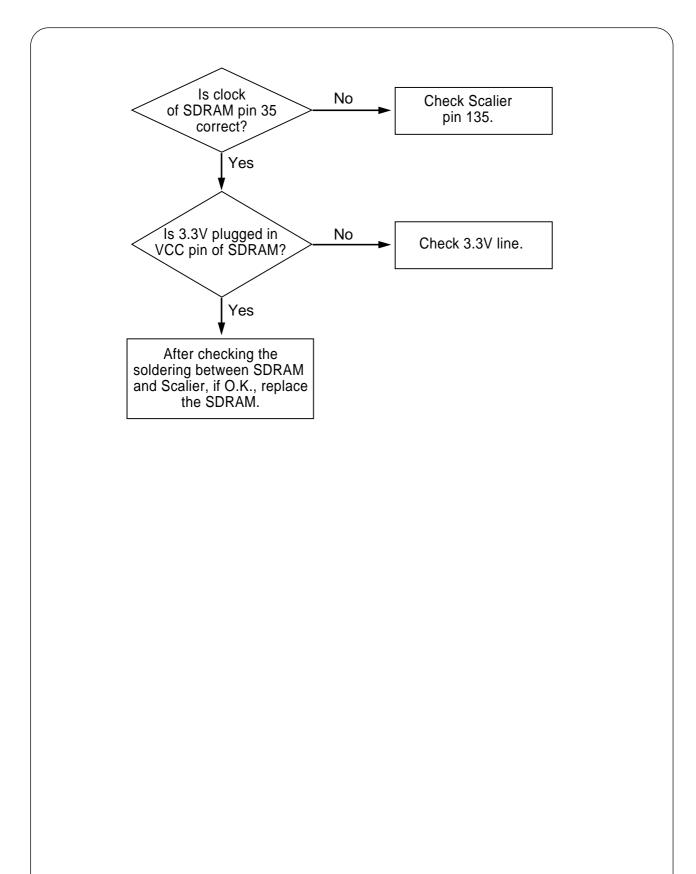
5. No Video

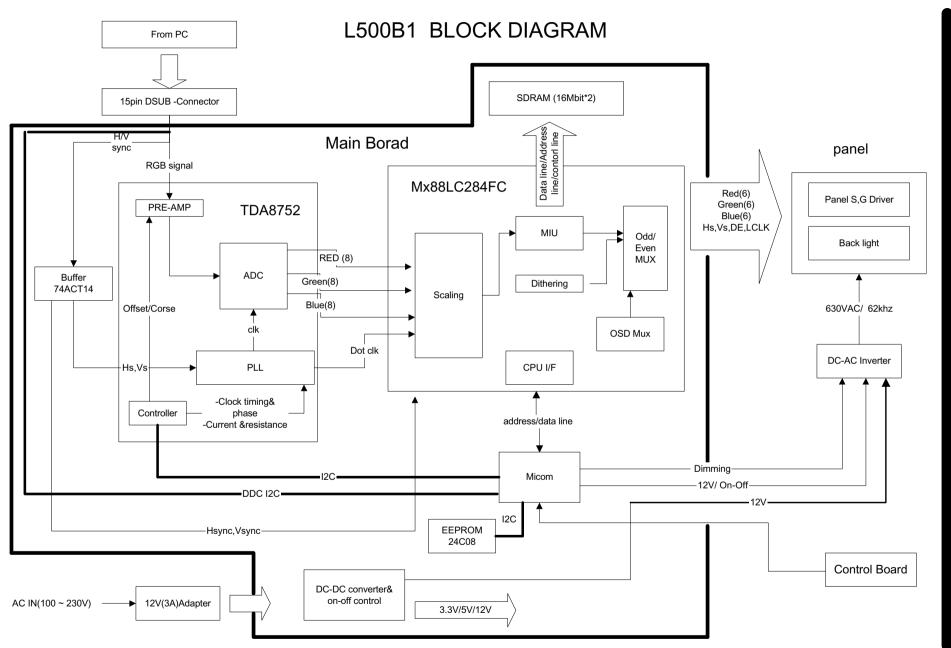


5-1. No Video



6. Broke graph

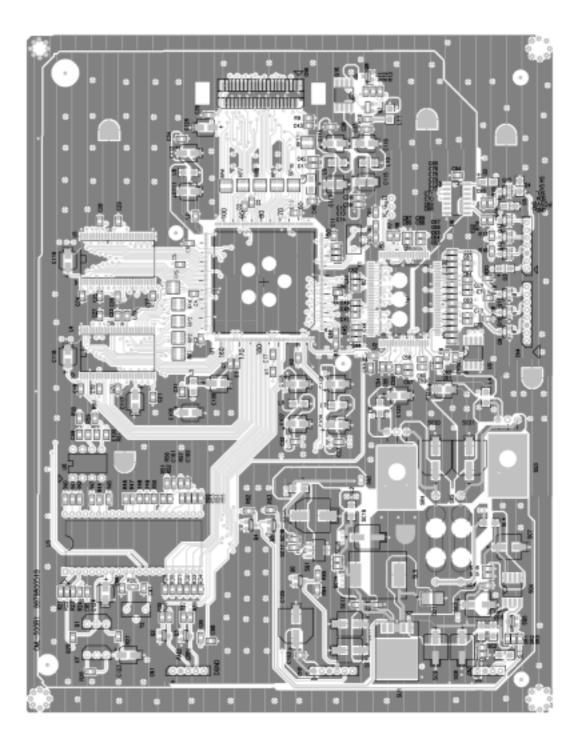




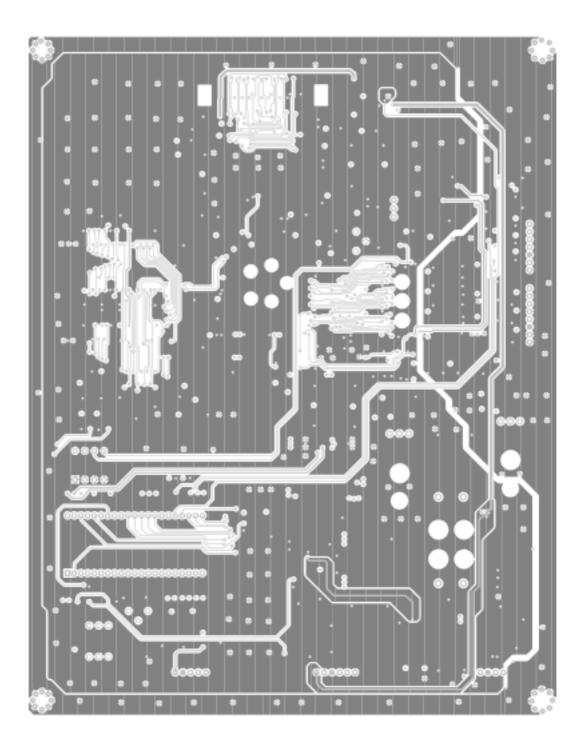
BLOCK DIAGRAM

PCB LAYOUT

Main PCB Component Side

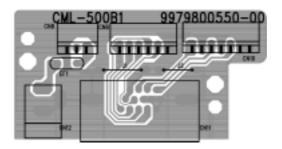


Main PCB Solder Side

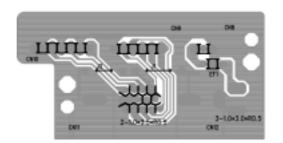


Control PCB Component Side Control PCB Solder Side CML-500B1 9979800550-00 8

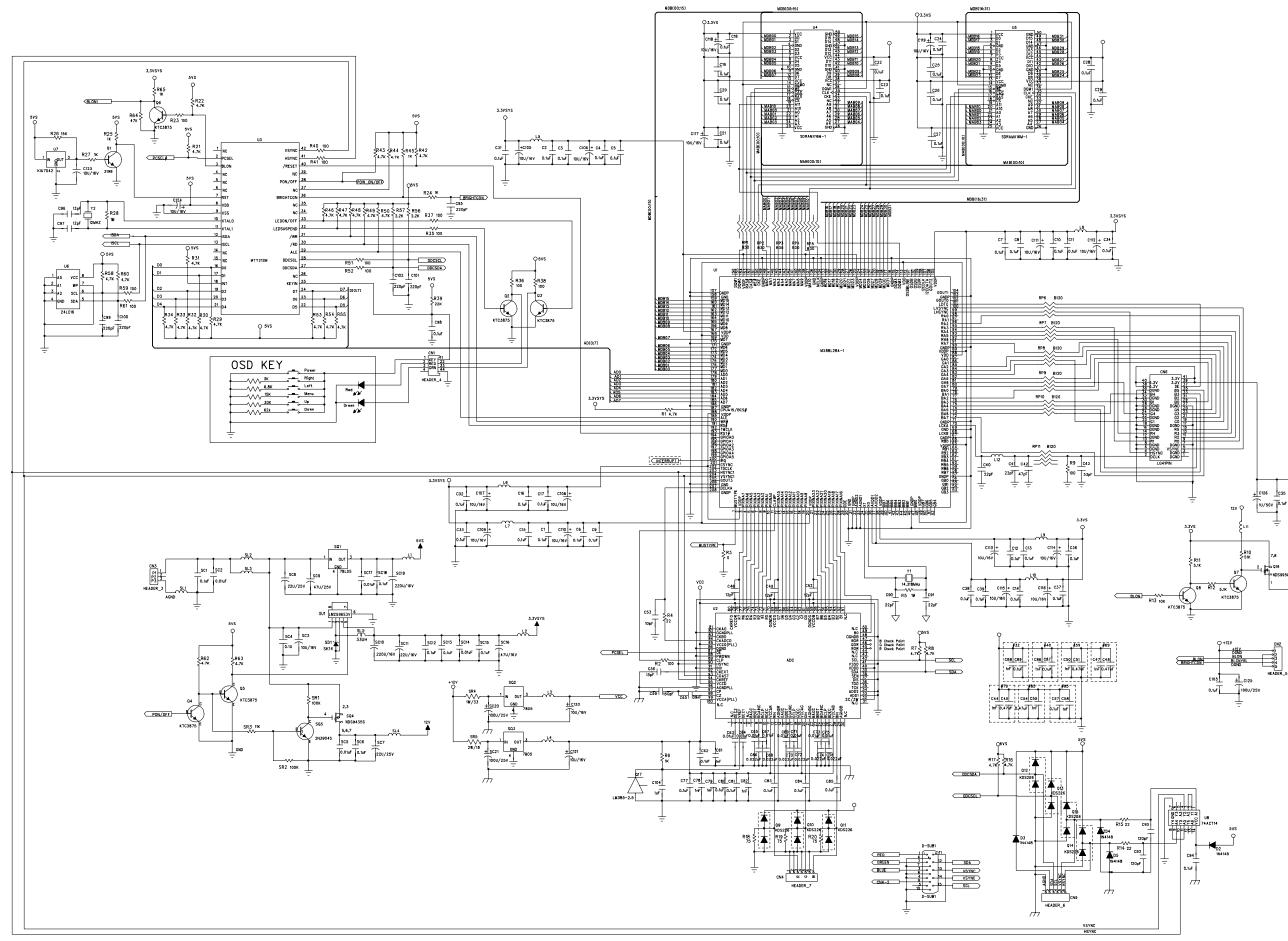
D-sub PCB Component Side



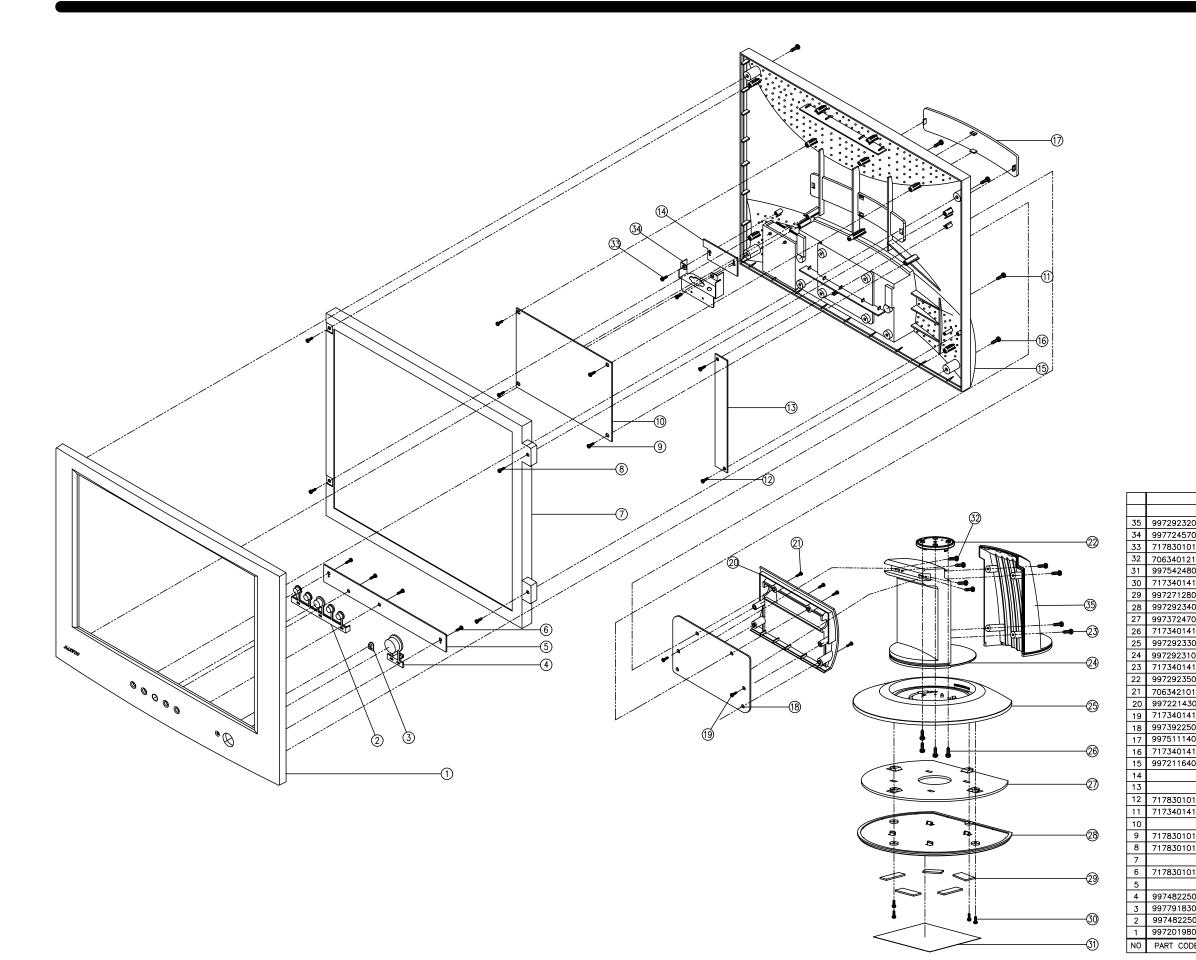
D-sub PCB Solder Side



SCHEMATIC DIAGRAM



EXPLODED VIEW & MECHANICAL PARTS LIST



200	STAND REAR	1	HB-ABS GY-275A(94-HB)	
700	SHIELD CONNECTOR	1	EGI 0.8T	BKT REAR+REAR
011	SCREW TAPTITE	2	TT2 WAS 3x10 MFZN	
211	SCREW MACHINE	4	M/S BIN 4*12 MFZN SW	HINGE+ST/FRONT
800	LABEL RATING	1	PE	
411	SCREW TAPTITE	4	TT2 BIN 4x14 MFZN	ST/TOP+ST/BOTTOM
800	FOOT	5	RUBBER	
400	STAND BOTTOM	1	HB-ABS GY-275A(94-HB)	
700	SUPPORTER STAND	1	EGI 3.0T	
411	SCREW TAPTITE	4	TT2 BIN 4x14 MFZN	ST/TOP+FRIC/ PAD
300	STAND TOP	1	HB-ABS GY-275A(94-HB)	
100	STAND FRONT	1	HB-ABS GY-275A(94-HB)	
411	SCREW TAPTITE	4	TT2 BIN 4x14 MFZN	ST/FRO+ST/REAR
500	FRICTION PAD	1	PC+ABS GY-275A	
011	SCREW MACHINE	4	M/S BIN 4*12 MFZN SW	STAND AS+REAR
300	COVER MOUNT	1	HB-ABS GY-275A(94-HB)	
411	SCREW TAPTITE	2	TT2 BIN 4x14 MFZN	CO/MOUNT+HINGE
500	BKT HINGE ASS'Y	1	SUS 1.5T	
400	DECO PANEL	1	HB-ABS GY-275A(94-HB)	
411	SCREW TAPTITE	4	TT2 BIN 4x14 MFZN	FRONT+REAR
400	COVER REAR	1	FR-ABS GY-275A	
	SUB PCB	1		
	INBERTER PCB	1		
011	SCREW TAPTITE	2	TT2 WAS 3x10 MFZN	
411	SCREW TAPTITE	1	TT2 BIN 4x14 MFZN	
	MAIN PCB	1		
011	SCREW TAPTITE	4	TT2 WAS 3x10 MFZN	
011	SCREW TAPTITE	4	TT2 WAS 3x10 MFZN	
	LCD PANEL	1		
011	SCREW TAPTITE	4	TT2 WAS 3x10 MFZN	
	CONTROL PCB	1		
500	BUTTON POWER	1	HB-ABS GY-275A(94-HB)	
300	LENS LED	1	ACRYL	
2500	BUTTON POWER	1	HB-ABS GY-275A(94-HB)	
800	COVER FRONT	1	FR-ABS GY-275A	
DDE	PART NAME	Q'TY	DESCRIPTION	REMARK
				-

INFORMATION OF PART DESCRIPTION

Important Safety Notice

Components identified with the International Symbol have special characteristics important for safety. When replacing any components, use only manufacturer's specified parts.

Abbreviation of Description

RESISTOR Description

KEDIDIO	K Description		
Г	Tolerance		
F	± 1%		
J	± 5%	<	
K	± 10%		
M	± 20%		
G	± 2%		
Example:			
Fig &	De et Ne	Description	

	Fig & Index	Part No	Description
	R101	Resist	tors
		RD-4Z820J	Carbon : 82 <u>J</u>
	R30	HRFS472JBA	Chip 4.7K OHM <u>J</u>

CAPACITOR Description

r	Tolerance	
С	± 0.25pF	
D	$\pm 0.5\%$	
F	± 1pF	
J	± 5%	<
Κ	± 10%	<
Р	$\pm 100\% \thicksim 0\%$	
Ζ	± 80% ~ -	<

Example:

Fig & Index	Part No	Description	
	Capacit	tors	
C28	HCFK104ZBA	Chip Cera 50V Z	
C63	HCBK393KBA	Chip Cera 50V K	
C44	HCQK102JBA	Chip Cera 50V J	

ELECTRICAL PARTS LIST

The components identified by mark \triangle have special characteristics important for safety and x-ray radiation. These should be replaced only with the types specified in the parts list.

	LOC	PART-CODE	PART-NAME	PART-DESC	LOC	PART-CODE	PART-NAME	PART-DESC
	00030	9970800035	CABLE SIGNAL AS	15P+15P/DDC=1.5M(GY275A)	C28	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
	00040	W1112B831-	CORD POWER	CML-100 1.8M BK(AME)	C29	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
	01000	9979800550	PCB CONTROL	T=1.6*246*122	C3	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
⚠	AD1	9979720013	ADAPTER POWER	LSE9802B1240(DC12V/3.3A)	C31	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
	C1	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C32	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
	C10	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C33	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
	C100	HCQK221JBA	C CHIP CERA	50V CH 220PF J 1608	C34	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
	C101	HCQK221JBA	C CHIP CERA	50V CH 220PF J 1608	C35	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
	C102	HCQK221JBA	C CHIP CERA	50V CH 220PF J 1608	C36	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
	C103	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C37	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
	C104	HCFD105ZBA	C CHIP CERA	Y5V 10V 1MF Z 1608	C38	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
	C106	HCEKF100MC	C CHIP ELECTRO	MV 16V 10MF D4.0XH5.2	C39	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
	C108	HCEKF100MC	C CHIP ELECTRO	MV 16V 10MF D4.0XH5.2	C4	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
	C11	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C40	HCQK220JBA	C CHIP CERA	50V CH 22PF J 1608
	C110	HCEKF100MC	C CHIP ELECTRO	MV 16V 10MF D4.0XH5.2	C41	HCQK220JBA	C CHIP CERA	50V CH 22PF J 1608
	C111	HCEKF100MC	C CHIP ELECTRO	MV 16V 10MF D4.0XH5.2	C42	HCQK470JBA	C CHIP CERA	50V CH 47PF J 1608
	C113	HCEKF100MC	C CHIP ELECTRO	MV 16V 10MF D4.0XH5.2	C43	HCQK330JBA	C CHIP CERA	50V CH 33PF J 1608
	C114	HCEKF100MC	C CHIP ELECTRO	MV 16V 10MF D4.0XH5.2	C44	HCQK102JBA	C CHIP CERA	50V CH 1000PF J 1608
	C115	HCEKF100MC	C CHIP ELECTRO	MV 16V 10MF D4.0XH5.2	C45	HCFF474ZBA	C CHIP CERA	Y5V 16V 0.47MF Z 1608
	C116	HCEKF100MC	C CHIP ELECTRO	MV 16V 10MF D4.0XH5.2	C46	HCQK120JBA	C CHIP CERA	50V CH 12PF J 1608
	C117	HCEKF100MC	C CHIP ELECTRO	MV 16V 10MF D4.0XH5.2	C47	HCQK102JBA	C CHIP CERA	50V CH 1000PF J 1608
	C118 C119	HCEKF100MC HCEKF100MC	C CHIP ELECTRO C CHIP ELECTRO	MV 16V 10MF D4.0XH5.2 MV 16V 10MF D4.0XH5.2	C48 C49	HCFF474ZBA	C CHIP CERA	Y5V 16V 0.47MF Z 1608 50V CH 12PF J 1608
	C119 C12	HCFK104ZBA	C CHIP ELECTRO	50V Y5V 0.1MF Z 1608	C49 C5	HCQK120JBA HCFK104ZBA	C CHIP CERA C CHIP CERA	50V Y5V 0.1MF Z 1608
	C12	HCEKF100MC	C CHIP ELECTRO	MV 16V 10MF D4.0XH5.2	C50	HCQK104ZBA	C CHIP CERA	50V CH 1000PF J 1608
	C120	HCEKF100MC	C CHIP ELECTRO	MV 16V 10MF D4.0XH5.2	C51	HCFF474ZBA	C CHIP CERA	Y5V 16V 0.47MF Z 1608
	C123	HCEKF100MC	C CHIP ELECTRO	MV 16V 10MF D4.0XH5.2	C52	HCQK120JBA	C CHIP CERA	50V CH 12PF J 1608
	C124	HCEKF100MC	C CHIP ELECTRO	MV 16V 10MF D4.0XH5.2	C54	HCFF474ZBA	C CHIP CERA	Y5V 16V 0.47MF Z 1608
	C125	HCENH101MD	C CHIP ELECTRO	MV 25V 100MF D8.0XH6.3	C55	HCQK102JBA	C CHIP CERA	50V CH 1000PF J 1608
	C126	HCEKK109MC	C CHIP ELECTRO	MV 50V 1MF D4.0XH5.2	C56	HCQK150JBA	C CHIP CERA	50V CH 15PF J 1608
	C13	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C57	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
	C14	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C58	HCQK102JBA	C CHIP CERA	50V CH 1000PF J 1608
	C15	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C59	HCQK151JBA	C CHIP CERA	50V CH 150PF J 1608
	C16	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C6	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
	C17	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C60	HCBK393KBA	C CHIP CERA	50V X7R 0.039MF K 1608
	C18	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C61	HCQK102JBA	C CHIP CERA	50V CH 1000PF J 1608
	C19	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C62	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
	C2	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C63	HCBK103KBA	C CHIP CERA	50V X7R 0.01MF K 1608
	C20	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C64	HCBK103KBA	C CHIP CERA	50V X7R 0.01MF K 1608
	C21	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C65	HCBK103KBA	C CHIP CERA	50V X7R 0.01MF K 1608
	C22	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C66	HCBK223KBA	C CHIP CERA	50V X7R 0.022MF K 1608
	C23	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C67	HCBK103KBA	C CHIP CERA	50V X7R 0.01MF K 1608
	C24	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C68	HCBK223KBA	C CHIP CERA	50V X7R 0.022MF K 1608
	C25	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C69	HCBK103KBA	C CHIP CERA	50V X7R 0.01MF K 1608
	C26	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C7	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
	C27	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	C70	HCBK223KBA	C CHIP CERA	50V X7R 0.022MF K 1608

LOC	PART-CODE	PART-NAME	PART-DESC	LOC	PART-CODE	PART-NAME	PART-DESC
C71	HCBK103KBA	C CHIP CERA	50V X7R 0.01MF K 1608	L1	HFFTB2601B	COIL CHIP BEAD	TB321611Z260
C72	HCBK223KBA	C CHIP CERA	50V X7R 0.022MF K 1608	L10	HFFTB2601B	COIL CHIP BEAD	TB321611Z260
C73	HCBK103KBA	C CHIP CERA	50V X7R 0.01MF K 1608	L11	HFFTB2601B	COIL CHIP BEAD	TB321611Z260
C74	НСВК223КВА	C CHIP CERA	50V X7R 0.022MF K 1608	L12	HFFTB2601B	COIL CHIP BEAD	TB321611Z260
C75	HCBK103KBA	C CHIP CERA	50V X7R 0.01MF K 1608	L2	HFFTB2601B	COIL CHIP BEAD	TB321611Z260
C76	HCBK223KBA	C CHIP CERA	50V X7R 0.022MF K 1608	L3	HFFTB2601B	COIL CHIP BEAD	TB321611Z260
C77	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	L4	HFFTB2601B	COIL CHIP BEAD	TB321611Z260
C78	HCQK102JBA	C CHIP CERA	50V CH 1000PF J 1608	L5	HFFTB2601B	COIL CHIP BEAD	TB321611Z260
C79	HCQK102JBA	C CHIP CERA	50V CH 1000PF J 1608	L6	HFFTB2601B	COIL CHIP BEAD	TB321611Z260
C8	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	L7	HFFTB2601B	COIL CHIP BEAD	TB321611Z260
C80	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	L8	HFFTB2601B	COIL CHIP BEAD	TB321611Z260
C81	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	L9	HFFTB2601B	COIL CHIP BEAD	TB321611Z260
C82	HCQK102JBA	C CHIP CERA	50V CH 1000PF J 1608	LCD	DLM151X2C2	LCD	LM151X2-C2TH
C83	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	LED1	DSD50GYW	LED	SD50GYW(GREEN/AMBER)
C84	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	OUTA	9970741001	CONN AS	DF-9-41S*2+1571#32=220
C85	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	PCB1	9979800549	PCB MAIN	T=1.6*180*140
C86	HCQK102JBA	C CHIP CERA	50V CH 1000PF J 1608	Q1	TZTC3198Y-	TR	KTC3198Y-(1815Y) (AUTO)
C87	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	Q10	DKDS226RTK	DIODE CHIP	KDS226(RTK)
C88	HCQK102JBA	C CHIP CERA	50V CH 1000PF J 1608	Q11	DKDS226RTK	DIODE CHIP	KDS226(RTK)
C89	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	Q12	DKDS226RTK DKDS226RTK	DIODE CHIP	KDS226(RTK)
C9	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	Q12 Q13	DKDS226RTK DKDS226RTK	DIODE CHIP	KDS226(RTK)
C90	HCQK220JBA	C CHIP CERA	50V CH 22PF J 1608	Q13	DKDS226RTK DKDS226RTK	DIODE CHIP	KDS226(RTK)
C90	HCQK220JBA	C CHIP CERA	50V CH 22PF J 1608	Q14 Q15	DKDS226RTK DKDS226RTK	DIODE CHIP	KDS226(RTK)
C91	HCQK121JBA	C CHIP CERA	50V CH 120PF J 1608	Q15 Q16	TNDS9958	FET CHIP	NDS9958
C92	HCQK121JBA HCQK121JBA	C CHIP CERA	50V CH 120PF J 1608	Q10 Q2	TKTC3875SY	TR CHIP	KTC3875SY(RTK)
C93	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	Q2 Q3	TKTC3875SY	TR CHIP	KTC3875SY(RTK)
C95	HCQK221JBA	C CHIP CERA	50V CH 220PF J 1608	Q4	TKTC3875SY	TR CHIP	KTC3875SY(RTK)
C95	HCQK120JBA	C CHIP CERA	50V CH 12PF J 1608	Q4 Q5	TKTC3875SY	TR CHIP	KTC3875SY(RTK)
C90 C97	HCQK120JBA HCQK120JBA	C CHIP CERA	50V CH 12PF J 1608	Q6	TKTC3875SY	TR CHIP	KTC3875SY(RTK)
C97	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608	Q0 Q7	TKTC3875SY	TR CHIP	KTC3875SY(RTK)
C98	HCQK221JBA	C CHIP CERA	50V CH 220PF J 1608	Q9	DKDS226RTK	DIODE CHIP	KDS226(RTK)
	-						
CN10	9979220022	CONN WAFER	SMAW250-07 (ANGLE)	R1	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608
CN11	9979200209	D-SUB 15P ANGLE	15P DDC BLUE W/IN SCREW	R10	HRFS513JBA	R CHIP	1/16 51K OHM J 1608
CN12	9979100010	JACK DC	POWER JACK 6.5PIE 14.5*9	R12	HRFS512JBA	R CHIP	1/16 5.1K OHM J 1608
	9970740044	CONN AS	SMH250-04+YBNH200-05=270	R14	HRFS220JBA	R CHIP	1/16W 22 OHM J 1608
	9970750035	CONN AS	5264-05+YBNH200+1007=110	R15	HRFS220JBA	R CHIP	1/16W 22 OHM J 1608
CN3A	9970730072	CONN AS	SMH250+YBNH200+1354=250	R16	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608
CN4A	9970760045	CONN AS	SMH250+YBNH200+2464=120	R17	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608
CN5A	9970770030	CONN AS	SMH250+YBNH200+1354=180	R18	HRFS750JBA	R CHIP	1/16W 75 OHM J 1608
CN6	9979220080	CONN WAFER	DF9B-41P-1V(22)	R19	HRFS750JBA	R CHIP	1/16W 75 OHM J 1608
CN7	9979220019	CONN WAFER	SMAW250-04 (ANGLE)	R2	HRFS101JBA	R CHIP	1/16 100 OHM J 1608
CN8	9979220018	CONN WAFER	SMAW250-03 (ANGLE)	R20	HRFS750JBA	R CHIP	1/16W 75 OHM J 1608
CN9	9979220021	CONN WAFER	SMAW250-06 (ANGLE)	R21	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608
D2	DRLS4148	DIODE CHIP	RLS4148	R22	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608
D3	DRLS4148	DIODE CHIP	RLS4148	R23	HRFS101JBA	R CHIP	1/16 100 OHM J 1608
D4	DRLS4148	DIODE CHIP	RLS4148	R24	HRFS102JBA	R CHIP	1/16 1K OHM J 1608
D5	DRLS4148	DIODE CHIP	RLS4148	R25	HRFS102JBA	R CHIP	1/16 1K OHM J 1608
EF1	5PF1BH471M	FILTER LC	CFI-06-B-1H-471M	R26	HRFS153JBA	R CHIP	1/16 15K OHM J 1608
INV1	DBA11502	LCD INVERTER	BAI-1502	R27	HRFS102JBA	R CHIP	1/16 1K OHM J 1608

			PART-DESC	LOC	PART-CODE	PART-NAME	PART-DESC
28	HRFS105JBA	R CHIP	1/16 1M OHM J 1608	R9	HRFS101JBA	R CHIP	1/16 100 OHM J 1608
29	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	RP1	HFFH4H300E	COIL CHIP BEAD	HB-4H3216-300JT
3	HRFS000JBA	R CHIP	1/16 0 OHM J 1608	RP10	HFFH4M121E	COIL CHIP BEAD	HB-4M3216-121JT
.30	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	RP11	HFFH4M121E	COIL CHIP BEAD	HB-4M3216-121JT
31	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	RP2	HFFH4H300E	COIL CHIP BEAD	HB-4H3216-300JT
32	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	RP3	HFFH4H300E	COIL CHIP BEAD	HB-4H3216-300JT
33	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	RP4	HFFH4H300E	COIL CHIP BEAD	HB-4H3216-300JT
34	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	RP5	HFFH4H300E	COIL CHIP BEAD	HB-4H3216-300JT
35	HRFS101JBA	R CHIP	1/16 100 OHM J 1608	RP6	HFFH4M121E	COIL CHIP BEAD	HB-4M3216-121JT
36	HRFS221JBA	R CHIP	1/16 220 OHM J 1608	RP7	HFFH4M121E	COIL CHIP BEAD	HB-4M3216-121JT
37	HRFS101JBA	R CHIP	1/16 100 OHM J 1608	RP8	HFFH4M121E	COIL CHIP BEAD	HB-4M3216-121JT
38	HRFS221JBA	R CHIP	1/16 220 OHM J 1608	RP9	HFFH4M121E	COIL CHIP BEAD	HB-4M3216-121JT
39	HRFS223JBA	R CHIP	1/16 22K OHM J 1608	SC1	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
40	HRFS101JBA	R CHIP	1/16 100 OHM J 1608	SC10	HCEMF470MD	C CHIP ELECTRO	MV 16V 47MF D6.3XH5.2
41	HRFS101JBA	R CHIP	1/16 100 OHM J 1608	SC11	HCEMH220MD	C CHIP ELECTRO	MV 25V 22MF D6.3XH5.2
42	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	SC12	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
43	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	SC13	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
.44	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	SC14	HCBK103KBA	C CHIP CERA	50V X7R 0.01MF K 1608
45	HRFS102JBA	R CHIP	1/16 1K OHM J 1608	SC15	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
46	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	SC16	HCEMF470MD	C CHIP ELECTRO	MV 16V 47MF D6.3XH5.2
47	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	SC17	HCBK103KBA	C CHIP CERA	50V X7R 0.01MF K 1608
48	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	SC18	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
49	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	SC19	HCEPF221ME	C CHIP ELECTRO	MV 16V 220MF D8.0XH1.0
5	HRFS105JBA	R CHIP	1/16 1M OHM J 1608	SC2	HCBK103KBA	C CHIP CERA	50V X7R 0.01MF K 1608
50	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	SC20	HCENH101MD	C CHIP ELECTRO	MV 25V 100MF D8.0XH6.3
51	HRFS101JBA	R CHIP	1/16 100 OHM J 1608	SC21	HCENH101MD	C CHIP ELECTRO	MV 25V 100MF D8.0XH6.3
52	HRFS101JBA	R CHIP	1/16 100 OHM J 1608	SC3	HCEKF100MC	C CHIP ELECTRO	MV 16V 10MF D4.0XH5.2
53	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	SC4	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
54	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	SC5	HCBK103KBA	C CHIP CERA	50V X7R 0.01MF K 1608
55	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	SC6	HCFK104ZBA	C CHIP CERA	50V Y5V 0.1MF Z 1608
56	HRFS222JBA	R CHIP	1/16 2.2K OHM J 1608	SC7	HCEMH220MD	C CHIP ELECTRO	MV 25V 22MF D6.3XH5.2
57	HRFS222JBA	R CHIP	1/16 2.2K OHM J 1608	SC8	HCEMH220MD		MV 25V 22MF D6.3XH5.2
58	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	SC9	HCEEH470MD	C CHIP ELECTRO	MV 25V 47MF D6.3XH5.7
59	HRFS101JBA	R CHIP	1/16 100 OHM J 1608	SD1	DSK14	DIODE SCHOTTKY	SK14
6	HRFS101JBA	R CHIP	1/16 1K OHM J 1608	SL1	HFFTB2601B	COIL CHIP BEAD	TB321611Z260
60	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	SL1 SL2	HFFTB2601B	COIL CHIP BEAD	TB321611Z260
61	HRFS101JBA	R CHIP	1/16 100 OHM J 1608	SL2 SL3	HFFTB2601B	COIL CHIP BEAD	TB321611Z260
62	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	SL3	HFFTB2601B	COIL CHIP BEAD	TB321611Z260
63	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	SL4	HLC330M00E	L CHIP COIL	33UH M (BA330)
64	HRFS472JBA	R CHIP	1/16 47K OHM J 1608	SQ1	1K1A78L05F	IC REGULATOR CHIP	
65	HRFS102JBA	R CHIP	1/16 1K OHM J 1608	SQ1 SQ2	1K1A7805P1	IC REGULATOR CITI	KIA7805API
66	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	SQ2 SQ3	1K1A7805P1	IC REGULATOR	KIA7805API
7	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	SQ3	TNDS9435A-	FET CHIP	NDS9435A
8	HRFS472JBA	R CHIP	1/16 4.7K OHM J 1608	SQ4 SQ5	T2N3904SRT	TR CHIP	2N3904S(RTK)
o 80	RD-AZ302J-	R CARBON FILM	1/6 3K OHM J	SQ3 SR1	HRFS104JBA	R CHIP	1/16 100K OHM J 1608
.80	RD-AZ502J- RD-AZ682J-	R CARBON FILM	1/6 6.8K OHM J	SR1 SR2	HRFS104JBA	R CHIP	1/16 100K OHM J 1608
.81	RD-AZ082J- RD-AZ153J-	R CARBON FILM	1/6 15K OHM J	SR2 SR3	HRFS104JBA HRFS113JBA	R CHIP	1/16 11K OHM J 1608
	RD-AZ153J- RD-AZ303J-		1/6 30K OHM J	SR3 SR4	RS01Z330J-	R M-OXIDE FILM	1/10 11K OHM J 1008 1W 33 OHM J (TAPPING)
a 1	IND-ML303J-	R CARBON FILM	1/0 JUK URINI J	51(4	N201722001-	K WI-UAIDE FILM	1 w 55 URIVI J (TAPPING)

LOC	PART-CODE	PART-NAME	PART-DESC
SU1	1LM2596S33	IC SD REGULATOR	LM2596S3.3
SW1	5S50101Z10	SW TACT	KPT-1115AM
SW2	5S50101Z10	SW TACT	KPT-1115AM
SW3	5S50101Z10	SW TACT	KPT-1115AM
SW4	5S50101Z10	SW TACT	KPT-1115AM
SW5	5S50101Z10	SW TACT	KPT-1115AM
SW6	5S50101Z10	SW TACT	KPT-1115AM
U1	1MX88L284F	IC LCD CONTROLLER	MX88L284
U2	1TDA8752BH	IC ADC	TDA8752BH
U3	1MTV212M	IC MICOM	MTV212MS64U

LOC	PART-CODE	PART-NAME	PART-DESC
U3A	9979300501	SOCKET IC	SDIF-42T(1.778)
U4	1EM636165T	IC SDRAM	EM636165TS-8
U5	1EM636165T	IC SDRAM	EM636165TS-8
U6	124C08	IC EEPROM	24C08
U7	1KA7542	IC VOTAGE DETECTOR	KA7542
U8	1TC74ACT14	IC	TC74ACT14FN
U9	1LM385M25-	IC VOLTAGE REFERENCE	LM385M25
Y1	5XJ14R318F	CRYSTAL QUARTZ	HC-49/S 14.31818MHZ 50PPM
Y2	5XJ12R000E	CRYSTAL QUARTZ	HC-49/S 12.00000MHZ 30PPM



DAEWOO ELECTRONICS CO., LT]

686, AHYEON-DONG MAPO-GU SEOUL, KOREA C.P.O. BOX 8003 SEOUL, KOREA TELEX : DWELEC K28177-8 CABLE : "DAEWOOELEC" E-mail : G7F00E@web.dwe.co.kr TEL : 82-32-510-7620 FAX : 82-32-510-7630